



WHITE ELECTRONIC DESIGNS

Product Change Notification

Date: 9/21/09

PRODUCT CHANGE NOTIFICATION (PCN) # 140A00164 Addendum

Subject: Product Part Numbers W3H32M64E-XSBX and W3H32M72E-XSBX.

Product Description: DDR2 208 Plastic BGA.

White Electronic Designs Corporation wishes to inform you of the following changes.

1. The die used on product part numbers W3H32M64E-XSBX and W3H32M72E-XSBX will be changing from Micron U27Y to U47A.
2. With the new U47A die the package size for the W3H32M72E-XSBX will be shrinking from 18mm x 20mm to 16mm x 20mm. As a result the W3H32M72E-XSBX will be EOL and the replacement part will be W3H32M72E-XSB2X. The BGA footprint and pin out remain the same.

Please contact your WEDC sales representative for specific product availability and a revised datasheet.

WEDC Engineering